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SEMICONDUCTOR DEVICE

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[There are no amendments to this patent.]

Claims

1. A semiconductor device in which at least two pallets are arranged to face each other with a lead frame in between, and with the electrode part of each pallet being bonded to the lead frame.

2. A semiconductor device described in Claim 1, characterized by a construction in which the electrode part of two pallets arranged to face each other with a lead frame in between is connected to this lead frame with solder bumps inside the package.

3. A semiconductor device described in Claim 1, characterized by a construction in which the pallet fixation part of the lead frame is composed of multiple steps and with two pallets each being arranged to face each other with the pallet fixation part of each step in between, and with the electrode part of each pallet and pallet fixation part being connected with solder bumps.

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